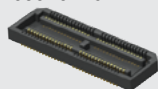


LSH-030-01-G-D-A



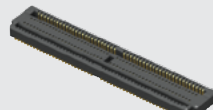
LSH-010-01-G-D-A



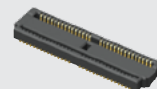
LSH-050-01-G-D-A



LTH-050-01-G-D-A



LTH-030-01-G-D-A



LTH-010-01-G-D-A



(0.50 mm) .0197"

LTH, LSH SERIES

# LOW PROFILE BLADE AND BEAM

LTH Mates with:

LSH

LSH Mates with:

LTH

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?LTH](http://www.samtec.com?LTH) or [www.samtec.com?LSH](http://www.samtec.com?LSH)

**Insulator Material:**

Liquid Crystal  
Polymer

**Terminal Material:**

Phosphor Bronze

**Contact Material:**

BeCu

**Plating:**

Au over 50 μ" (1.27 μm) Ni

**Operating Temp Range:**

-55 °C to +125 °C

**RoHS Compliant:**

Yes

## PROCESSING

**Lead-Free Solderable:**

Yes

**SMT Lead Coplanarity:**

(0.10 mm) .004" max

**Board Stacking:**

For applications requiring more than two connectors per board, contact [ipg@samtec.com](mailto:ipg@samtec.com)

## RECOGNITIONS

For complete scope of

recognitions see

[www.samtec.com/quality](http://www.samtec.com/quality)



FILE NO. E111594

## MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(2.31) .091

\*Processing conditions will affect mated height.

**Note:** Some lengths, styles and options are non-standard, non-returnable.

**LTH** — **NO. OF POSITIONS PER ROW** — **01** — **PLATING OPTION** — **D** — **A** — **OTHER OPTION**

**-010, -020, -030, -040, -050**

**-G**  
= 10 μ" (0.25 μm) Gold

**-K**  
= (5.50 mm) .217" DIA Polyimide Film Pick & Place Pad

**-TR**  
= Tape and Reel

**LSH** — **NO. OF POSITIONS PER ROW** — **01** — **PLATING OPTION** — **D** — **A** — **OTHER OPTION**

**-010, -020, -030, -040, -050**

**-G**  
= 10 μ" (0.25 μm) Gold

**-K**  
= (7.50 mm) .295" DIA Polyimide Film Pick & Place Pad

**-TR**  
= Tape and Reel